16 GB DDR4 SDRAM UDIMM Specification

Specifications

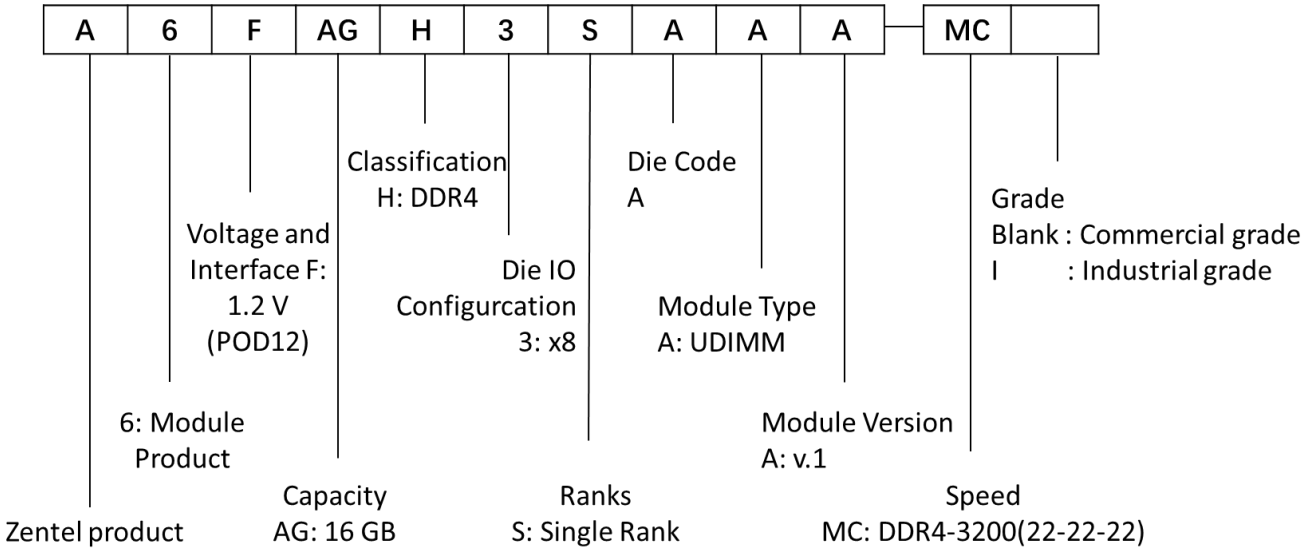
Max. Speed; CAS Latency	DDR4-3200@CL=22
Row Cycle Time (tRCmin)	45.75 ns
Row Active Time (tRASmin)	32 ns(min.)

Features

- 288-pin, unbuffered dual in-line memory module (UDIMM)
- 1Rx8 memory module (1 rank of x8 DDR4 SDRAMs)
- Power supply:
  - VDD = VDDQ = 1.2 V ± 5%
  - VPP = 2.5 V –5%/+10%
  - VDDSPD = 2.2 V to 3.6 V
- Nominal and dynamic on-die termination (ODT) for data, strobe, and mask signals
- Low-power auto self refresh (LPASR)
- Data bus inversion (DBI) for data bus
- On-die VREFDQ generation and calibration
- On-board I^2C serial presence-detect (SPD) EEPROM
- 16 internal banks; 4 groups of 4 banks each
- Fixed burst chop (BC) of 4 and burst length (BL) of 8 via the mode register set (MRS)
- Selectable BC4 or BL8 on-the-fly (OTF)
- Fly-by topology
- Terminated control command and address bus
- PCB Height: 1.23” (31.25 mm)

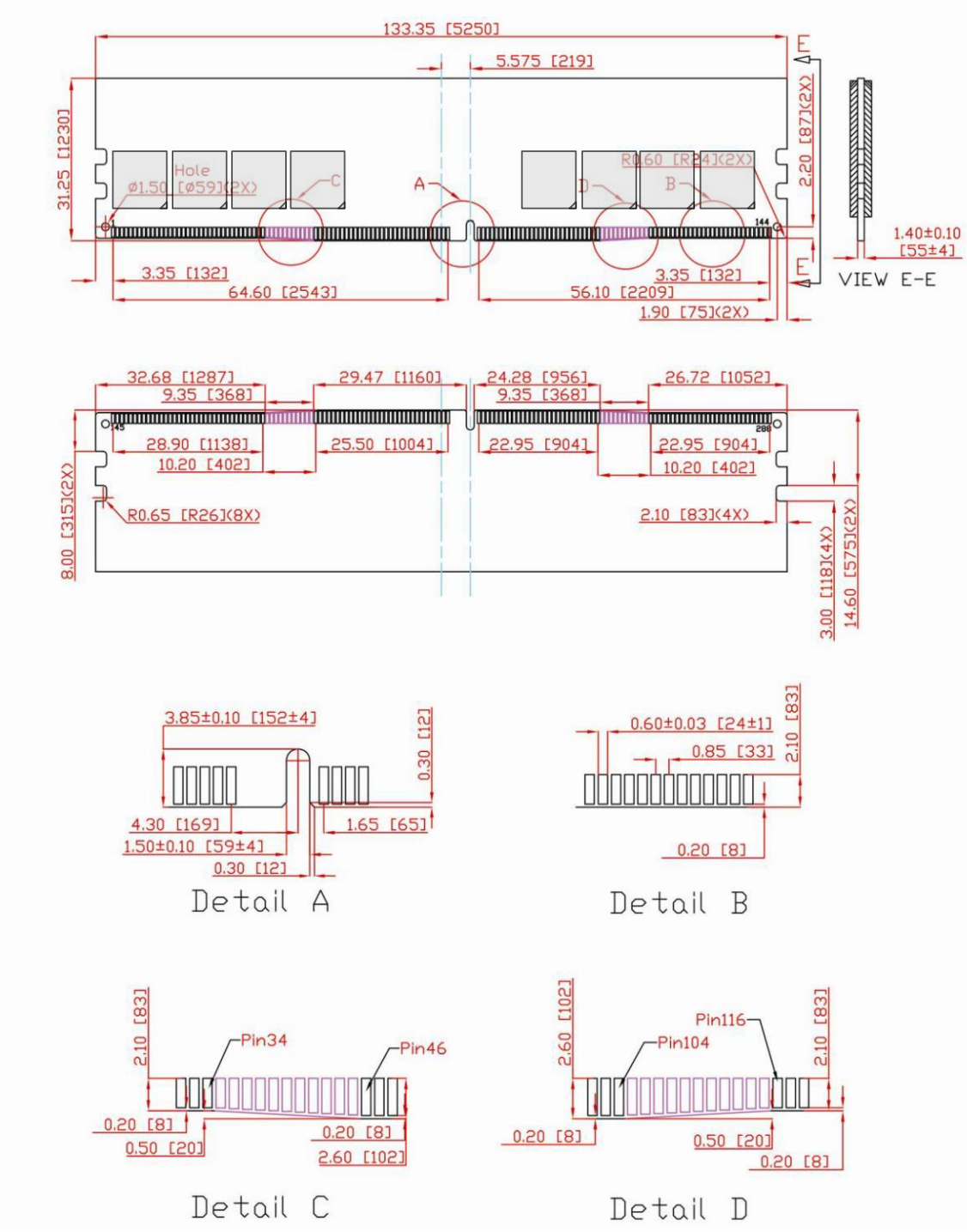
1. Ordering Information

Part Number	*Module Density*	*Configuration*	*Speed Bin (CL-nRCD-nRP)*	*Operating Temperature*	*Storage Temperature*
A6FAGH3SAAA-MC	16 GB	2G × 64 (2Gx8 1Rank)	DDR4-3200 (22-22-22)	0 °C to +85 °C	-55 °C to +100 °C
A6FAGH3SAAA-MCI				-40 °C to +85 °C	-55 °C to +150 °C



Module Dimensions

All dimensions are in millimeter[mils] and should be kept within a tolerance of +/- 0.15[6], unless otherwise specified.



Change History			
Document No.: DSA6FAGH3SAAAF.(Rev.#)			
Rev. #	**Who**	**When**	**What**
01	Rik	2023-05-04	Initial version derived from DSA6FAGH3SAAAZF.01; Updated header and footer
02	Abby	2023-05-10	Updated Ordering Information